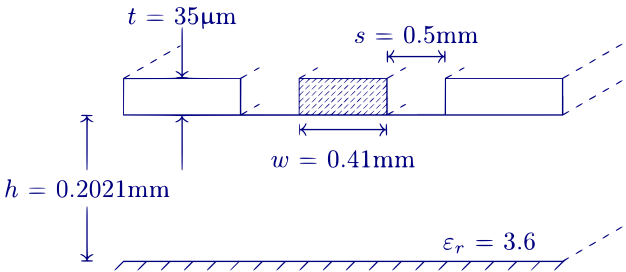
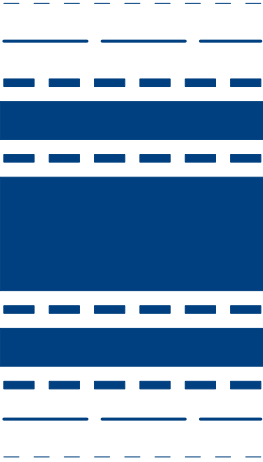
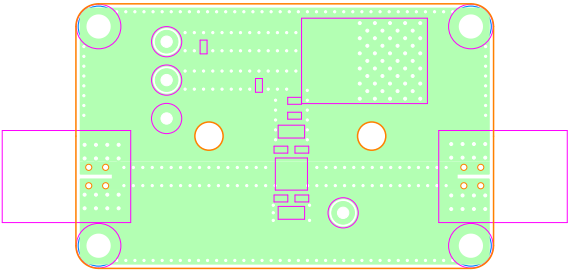


| Layer Material | Layer (File) Name | Thickness (mm) | Permittivity | Loss Tangent |
|----------------|-------------------|----------------|--------------|--------------|
| Silkscreen | F.Silk | 0.00762 | ---- | ---- |
| Soldermask | F.Mask | 0.0254 | 4.5 | 0.029 |
| Copper | F.Cu | 0.0432 | ---- | ---- |
| FR408HR 2113 | ----- | 0.2021 | 3.6 | 0.010 |
| Copper | In1.Cu | 0.0175 | ---- | ---- |
| FR408-HR | ----- | 0.9906 | 3.64 | 0.0098 |
| Copper | In2.Cu | 0.0175 | ---- | ---- |
| FR408HR 2113 | ----- | 0.2021 | 3.6 | 0.010 |
| Copper | B.Cu | 0.0432 | ---- | ---- |
| Soldermask | B.Mask | 0.0254 | 4.5 | 0.029 |
| Silkscreen | B.Silk | 0.00762 | ---- | ---- |



Hole pattern for Hammond 1554B



| Layer Material | Layer (File) Name | Thickness (mm) | Permittivity | Loss Tangent |
|----------------|-------------------|----------------|--------------|--------------|
| Silkscreen | F.Silk | 0.00762 | ----- | ----- |
| Soldermask | F.Mask | 0.0254 | 4.5 | 0.029 |
| Copper | F.Cu | 0.0432 | ----- | ----- |
| FR408HR 2113 | ----- | 0.2021 | 3.6 | 0.010 |
| Copper | In1.Cu | 0.0175 | ----- | ----- |
| FR408-HR | ----- | 0.9906 | 3.64 | 0.0098 |
| Copper | In2.Cu | 0.0175 | ----- | ----- |
| FR408HR 2113 | ----- | 0.2021 | 3.6 | 0.010 |
| Copper | B.Cu | 0.0432 | ----- | ----- |
| Soldermask | B.Mask | 0.0254 | 4.5 | 0.029 |
| Silkscreen | B.Silk | 0.00762 | ----- | ----- |

Hole pattern for Hammond 1554B

Remy Nguyen

| | |
|--|-----------------|
| Sheet: | |
| File: TSS-183A+.kicad_pcb | |
| Title: 5000-18000 MHz SMT Gain Block Amplifier | |
| Size: USLetter | Date: 5/30/2024 |
| KiCad E.D.A. pcbnew 7.0.5 | Rev: A |
| Id: 1/1 | |

IN-L3

A

B

C

D

| Layer Material | Layer (File) Name | Thickness (mm) | Permittivity | Loss Tangent |
|----------------|-------------------|----------------|--------------|--------------|
| Silkscreen | F.Silk | 0.00762 | ----- | ----- |
| Soldermask | F.Mask | 0.0254 | 4.5 | 0.029 |
| Copper | F.Cu | 0.0432 | ----- | ----- |
| FR408HR 2113 | ----- | 0.2021 | 3.6 | 0.010 |
| Copper | In1.Cu | 0.0175 | ----- | ----- |
| FR408-HR | ----- | 0.9906 | 3.64 | 0.0098 |
| Copper | In2.Cu | 0.0175 | ----- | ----- |
| FR408HR 2113 | ----- | 0.2021 | 3.6 | 0.010 |
| Copper | B.Cu | 0.0432 | ----- | ----- |
| Soldermask | B.Mask | 0.0254 | 4.5 | 0.029 |
| Silkscreen | B.Silk | 0.00762 | ----- | ----- |

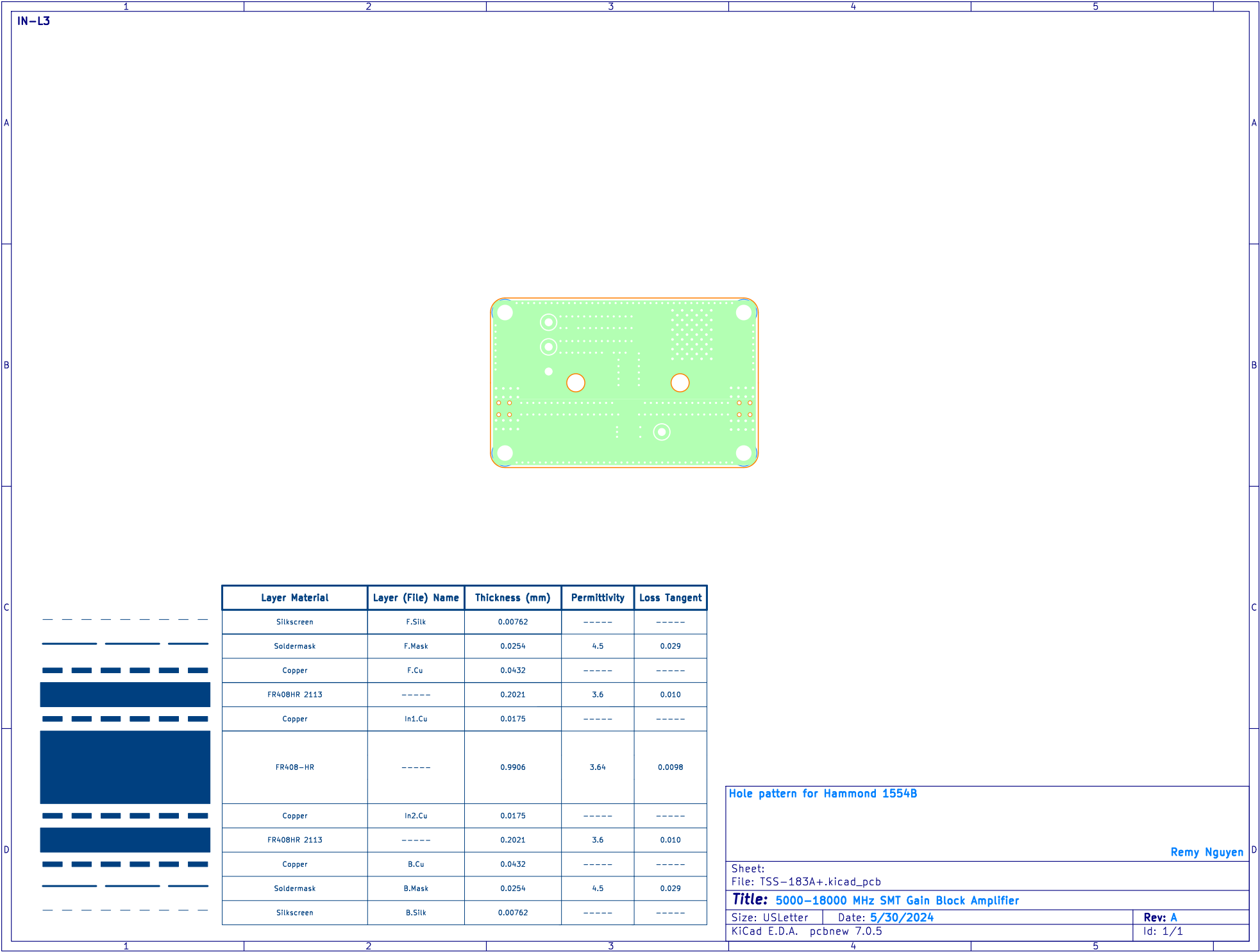
Hole pattern for Hammond 1554B

Sheet:
File: TSS-183A+.kicad_pcb

Title: 5000-18000 MHz SMT Gain Block Amplifier

Size: USLetter | Date: 5/30/2024 | Rev: A
KiCad E.D.A. pcbnew 7.0.5 | Id: 1/1

Remy Nguyen



IN-L3

A

B

C

D

1 2 3 4 5

| Layer Material | Layer (File) Name | Thickness (mm) | Permittivity | Loss Tangent |
|----------------|-------------------|----------------|--------------|--------------|
| Silkscreen | F.Silk | 0.00762 | ----- | ----- |
| Soldermask | F.Mask | 0.0254 | 4.5 | 0.029 |
| Copper | F.Cu | 0.0432 | ----- | ----- |
| FR408HR 2113 | ----- | 0.2021 | 3.6 | 0.010 |
| Copper | In1.Cu | 0.0175 | ----- | ----- |
| FR408-HR | ----- | 0.9906 | 3.64 | 0.0098 |
| Copper | In2.Cu | 0.0175 | ----- | ----- |
| FR408HR 2113 | ----- | 0.2021 | 3.6 | 0.010 |
| Copper | B.Cu | 0.0432 | ----- | ----- |
| Soldermask | B.Mask | 0.0254 | 4.5 | 0.029 |
| Silkscreen | B.Silk | 0.00762 | ----- | ----- |

Hole pattern for Hammond 1554B

Sheet:
File: TSS-183A+.kicad_pcb

Title: 5000-18000 MHz SMT Gain Block Amplifier

Size: USLetter | Date: 5/30/2024 | Rev: A
KiCad E.D.A. pcbnew 7.0.5 | Id: 1/1

Remy Nguyen

Hole pattern for Hammond 1554B

Remy Nguyen

Hole pattern for Hammond 1554B

Remy Nguyen

Sheet:
File: TSS-183A+.kicad_pcb

Sheet:
File: TSS-183A+.kicad_pcb

Title: 5000–18000 MHz SMT Gain Block Amplifier

| | |
|---------------------------|-----------------|
| Size: USLetter | Date: 5/30/2024 |
| KiCad E.D.A. pcbnew 7.0.5 | |

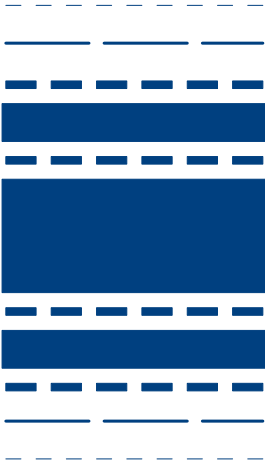
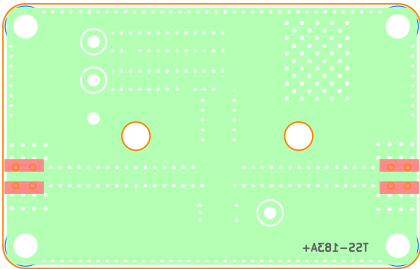
| | |
|---------------------------|-----------------|
| Size: USLetter | Date: 5/30/2024 |
| KiCad E.D.A. pcbnew 7.0.5 | |

| | |
|---------------------------|-----------------|
| Size: USLetter | Date: 5/30/2024 |
| KiCad E.D.A. pcbnew 7.0.5 | |

Rev: A
Id: 1/1

Rev: A
Id: 1/1

BOT-L4



| Layer Material | Layer (File) Name | Thickness (mm) | Permittivity | Loss Tangent |
|----------------|-------------------|----------------|--------------|--------------|
| Silkscreen | F.Silk | 0.00762 | ----- | ----- |
| Soldermask | F.Mask | 0.0254 | 4.5 | 0.029 |
| Copper | F.Cu | 0.0432 | ----- | ----- |
| FR408HR 2113 | ----- | 0.2021 | 3.6 | 0.010 |
| Copper | In1.Cu | 0.0175 | ----- | ----- |
| FR408-HR | ----- | 0.9906 | 3.64 | 0.0098 |
| Copper | In2.Cu | 0.0175 | ----- | ----- |
| FR408HR 2113 | ----- | 0.2021 | 3.6 | 0.010 |
| Copper | B.Cu | 0.0432 | ----- | ----- |
| Soldermask | B.Mask | 0.0254 | 4.5 | 0.029 |
| Silkscreen | B.Silk | 0.00762 | ----- | ----- |

Hole pattern for Hammond 1554B

Sheet:

File: TSS-183A+.kicad_pcb

Title: 5000-18000 MHz SMT Gain Block Amplifier

| | | |
|----------------|-----------------|---------|
| Size: USLetter | Date: 5/30/2024 | Rev: A |
| KiCad E.D.A. | pcbnew 7.0.5 | Id: 1/1 |